

REMARKS

The Examiner noted that the declaration was not in compliance with 37 CFR 1.67(a) for failing to identify the Priority Document to which priority is claimed. Applicants submit herewith a compliant declaration.

Claims 1-14 stand rejected under 35 USC 102(b) over Kang (U.S. Patent No. 6,323,669) and independently under 35 USC 102(b) over Ohba (U.S. Patent No. 6,323,666). Applicants have overcome these rejections by amending independent claim 1 to recite a testing method “wherein the semiconductor device comprises one or more contacts for testing the contacting between the semiconductor device and the carrier” and by amending independent claim 12 to recite a system comprising, “one or more contacts to test the contacting between the semiconductor device and the carrier.”

Kang and Ohba both disclose systems for checking the contacting between IC packages and the sockets of burn-in boards. This testing is performed to ensure that the IC packages are properly inserted into the sockets such that working IC packages are not rejected due to improper insertion. Such testing is disclosed in the Background section of Applicants’ specification. As further noted in Applicants’ specification, such testing does not determine if there is a contacting problem between the semiconductor devices and the carriers (packaging) that make up the IC packages. Therefore, when using the systems of Kang and Ohba it is not possible to tell if IC packages are failed due to improper contacting between the semiconductor devices and the carriers.

In contrast, the claimed invention (for example, in amended claims 1 and 12) recites contacts which are used to test the contacting between the semiconductor devices and the carriers. Using the claimed invention, it is possible to determine the cause of the failure of the device more accurately and therefore reduce costs and improve efficiency.

Neither Kang nor Ohba disclose or suggest a method or system for testing contacting between a semiconductor device and a carrier which comprises one or more contacts used exclusively for testing the contacting between the semiconductor device and the carrier. Both

Kang and Ohba disclose systems where the contacting between IC packages and sockets of burn-in boards in which they are inserted during testing. Applicants' claim a system and method which comprise contacts to test the connection between the semiconductor device and the carrier (i.e. the IC packaging). Neither Ohba nor Kang disclose testing the contacting between the semiconductor device and the carrier. Accordingly claims 1 and 12 are allowable over Kang and Ohba.

Claims 2-11, 13 and 14 depend from allowable base claims and are therefore also allowable.

Applicants solicit an early action allowing claims 1-14.

In the event that the transmittal letter is separated from this document, and the Patent and Trademark Office determines that an extension and/or other relief is required, applicants petition for any required relief, including extensions of time, and authorize the Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to **Deposit Account No. 03-1952** referencing 543822002400.

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